

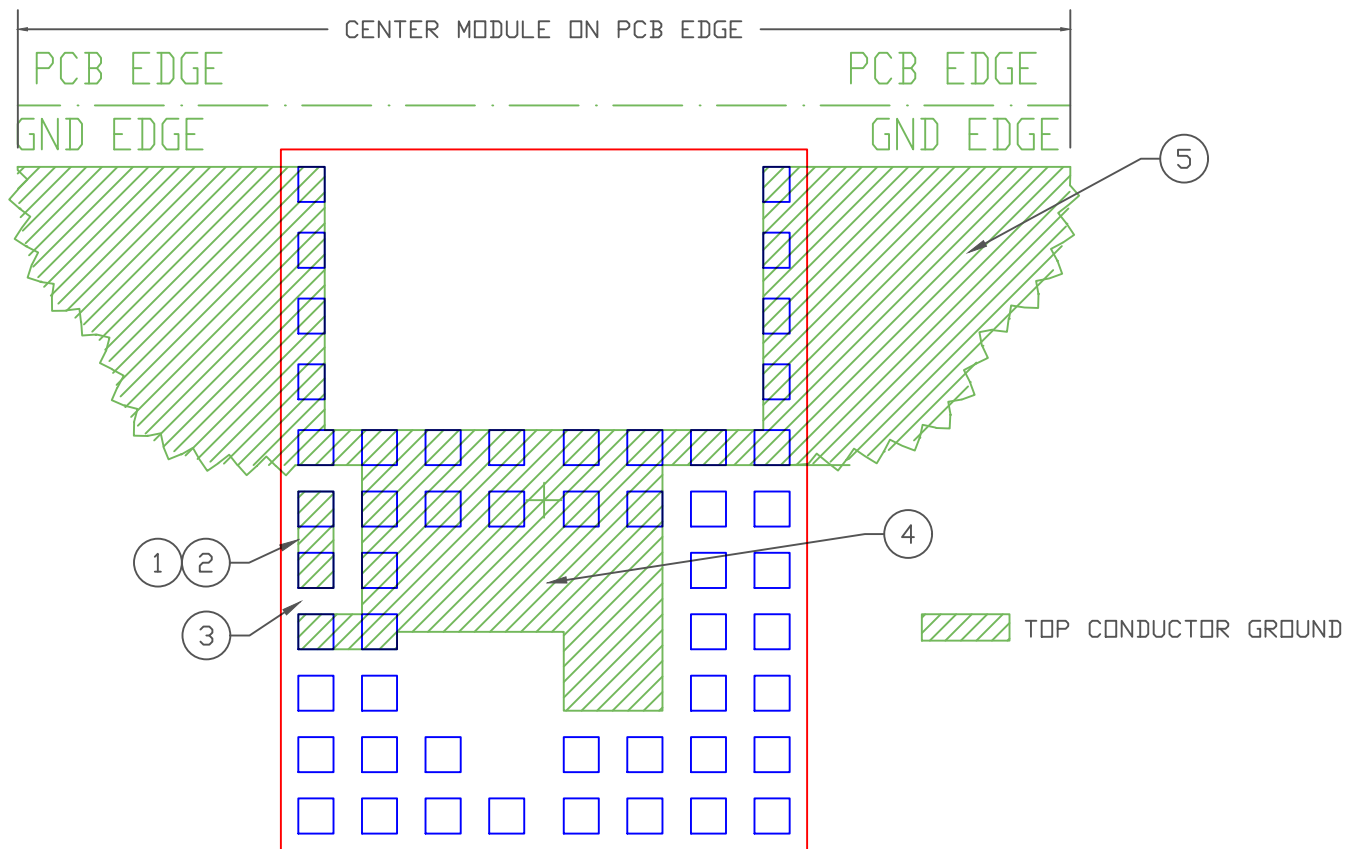
NOTES:

1. ALIGN COMPONENT EDGE TO PCB EDGE IF POSSIBLE.
2. EXTEND KEEPOUT AREA TO PCB EDGE.
3. KEEPOUT AREA - ALL LAYERS.
4. KEEPOUT AREA - TOP LAYER ONLY.
5. UNITS = MM.



ON Semiconductor

TITLE: KEEPOUT AREA REQUIREMENTS		
PART: NCH-RSL10-101S51		
DRAWN BY:	J. STEFFLER	DRAWING No.: TBD
CHECKED BY:	D. BANBURY	REV.: 0 DATE: 19/APR/18
APPROVED BY:	G. WEALE	PAGE: 1 OF 2



NOTES:

1. WHEN INCORPORATING INTERNAL ANTENNA, JOIN LANDING PADS USING 0.40×1.10 SHAPE.
2. ESTABLISH 50Ω IMPEDANCE TO UNDERLYING REFERENCE PLANE.
3. MAINTAIN MINIMUM $300\mu\text{M}$ DISTANCE FROM GROUND PLANE.
4. AREA FOR SEVERAL VIAS.
5. REFER TO RADIATION EFFICIENCY DATA FOR APPLICABLE GROUND PLANE SIZING.
6. UNITS = MM.



ON Semiconductor

TITLE: MINIMUM TOP LAYER GROUND STRUCTURE		
PART: NCH-RSL10-101S51		
DRAWN BY:	J.STEFFLER	DRAWING No.: TBD
CHECKED BY:	D.BANBURY	REV.: 0 DATE: 19/APR/18
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